ON Semiconductor

Update Notification

Document # : FPCN21390X1
Issue Date: 14 September 2016

Title of Change:	Update Notice of FPCN21390X – Change of proposed ship date of SSOP16, TSSOP20 (225mil), SSOP24, SSOP30 and TSSOP36 (275mil) package types.
Proposed first ship date:	3 August 2017
Contact information:	Contact your local ON Semiconductor Sales Office or <Takeshi2.Hoshino@onsemi.com>,<Yutaka.Okamura@onsemi.com>,<Takehito.Tsukui@onsemi.com>,<Shuichi.Takahashi@onsemi.com>,<Naoki.Koyama@onsemi.com>,<Shinya.Okada@onsemi.com>,<Ikuo.Saeki@onsemi.com>,<Hiroshi.Kojima@onsemi.com>,<Tetsuya.Fukushima@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☒ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable
☒ ON Semiconductor site(s) : ON Tarlac City, Philippines
☐ External Foundry/Subcon site(s) Select Site

Description and Purpose:

This Update Notice extends the **Proposed First Ship Date** of the previously released **FPCN21390X** from **3 November 2016** to **3 August 2017.**

FPCN21390X was previously announce the qualification of Lead Frame raw material change used in the ON Semiconductor SSOP16, TSSOP20 (225mil), SSOP24, SSOP30 and TSSOP36 (275mil) package type. The replacement of existing lead frame raw material from C50710 to C19400 (C50710/C19400: ASTM code). The reason is that the existing lead frame raw material will no longer be available.

The table below shows comparison of mechanical and chemical properties between the two materials.

Material Name		C19400(Alternative)	C50710(Existing)
Mechanical properties			
Coefficient of Thermal Expansion	$X10^{-6}/K$	17.6	17.0
Thermal Conductivity	W (m·K)	262	155
Electrical Resistivity	μΩm	0.025	0.054
Electrical Conductivity	%IACS	65	32
Modulus Elasticity	KN/mm^2	121	125
Chemical properties			
Cu	%	Remain	Remain
Zn	%	0.05 ~ 0.20	Max 0.20
Pb	%	Max 0.03	Max 0.02
Fe	%	2.10 ~ 2.60	Max 0.10
P	%	0.01 ~ 0.15	Max 0.15
Sn	%	None	1.70 ~ 2.30
Ni	%	None	0.10 ~ 0.40

List of Affected Standard Parts:

LB11600JV-TLM-E
LC72720YVS-TLM-E
LC72725KVS-H
LC75700TS-TLM-E
LC75700T-TLM-E
LC75814VS-TLM-E
LC75814V-TLM-E
LV3327PV-TLM-H

List of Affected Customer Specific Parts:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "Custom PCN for Selected Company Button" in the Document Analysis page of PCMS/PCN Alert.